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16th International Symposium on *Quality Electronic Design*

第16届高品质电子设计国际年会（中国，杭州）

16th ISQED is organized by the International Society for Quality Electronic Design with technical sponsorship from several IEEE Societies. The conference emphasizes innovations and the latest development in System and IC Design, Sensors, MEMS & NEMS, Semiconductor Technology & Manufacturing, IC Packaging & PCB Technology, Test, and Bio & Nano Electronics. **Past ISQED papers have been published in IEEE Xplore and ISQED proceedings and indexed in Scopus and EI.**



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Aug 18, 2014

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